

Welcome to E-XFL.COM

### What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

### Details

E·XFI

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	39
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f32ka304-i-ml

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

### TABLE 4-4: ICN REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CNPD1	0056	CN15PDE <sup>(1)</sup>	CN14PDE	CN13PDE	CN12PDE	CN11PDE	CN10PDE <sup>(1,2)</sup>	CN9PDE <sup>(1)</sup>	CN8PDE <sup>(3)</sup>	CN7PDE <sup>(1)</sup>	CN6PDE	CN5PDE	CN4PDE	CN3PDE	CN2PDE	CN1PDE	CNOPDE	0000
CNPD2	0058	CN31PDE <sup>(1,2)</sup>	CN30PDE	CN29PDE	CN28PDE <sup>(1,2)</sup>	CN27PDE <sup>(1)</sup>	CN26PDE <sup>(1,2)</sup>	CN25PDE <sup>(1,2)</sup>	CN24PDE <sup>(1)</sup>	CN23PDE	CN22PDE	CN21PDE	CN20PDE <sup>(1,2)</sup>	CN19PDE <sup>(1,2)</sup>	CN18PDE <sup>(1,2)</sup>	CN17PDE <sup>(1,2)</sup>	CN16PDE <sup>(1)</sup>	0000
CNPD3	005A	_	-	_	_	-	_	_	-	_	_	_	CN36PDE <sup>(1,2)</sup>	CN35PDE <sup>(1,2)</sup>	CN34PDE <sup>(1,2)</sup>	CN33PDE <sup>(1,2)</sup>	CN32PDE <sup>(1,2)</sup>	0000
CNEN1	0062	CN15IE <sup>(1)</sup>	CN14IE	CN13IE	CN12IE	CN11IE	CN10IE <sup>(1,2)</sup>	CN9IE <sup>(1)</sup>	CN8IE <sup>(3)</sup>	CN7IE <sup>(1)</sup>	CN6IE	CN5IE	CN4IE	CN3IE	CN2IE	CN1IE	CN0IE	0000
CNEN2	0064	CN31IE <sup>(1,2)</sup>	CN30IE	CN29IE	CN28IE <sup>(1,2)</sup>	CN27IE <sup>(1)</sup>	CN26IE <sup>(1,2)</sup>	CN25IE <sup>(1,2)</sup>	CN24IE <sup>(1)</sup>	CN23IE	CN22IE	CN21IE	CN20IE <sup>(1,2)</sup>	CN19IE <sup>(1,2)</sup>	CN18IE <sup>(1,2)</sup>	CN17IE <sup>(1,2)</sup>	CN16IE <sup>(1)</sup>	0000
CNEN3	0066	_		_	_	_	_	_	-	_	_	_	CN36IE <sup>(1,2)</sup>	CN35IE <sup>(1,2)</sup>	CN34IE <sup>(1,2)</sup>	CN33IE <sup>(1,2)</sup>	CN32IE <sup>(1,2)</sup>	0000
CNPU1	006E	CN15PUE <sup>(1)</sup>	CN14PUE	CN13PUE	CN12PUE	CN11PUE	CN10PUE <sup>(1,2)</sup>	CN9PUE <sup>(1)</sup>	CN8PUE <sup>(3)</sup>	CN7PUE <sup>(1)</sup>	CN6PUE	CN5PUE	CN4PUE	<b>CN3PUE</b>	CN2PUE	CN1PUE	CNOPUE	0000
CNPU2	0070	CN31PUE <sup>(1,2)</sup>	CN30PUE	CN29PUE	CN28PUE <sup>(1,2)</sup>	CN27PUE <sup>(1)</sup>	CN26PUE <sup>(1,2)</sup>	CN25PUE <sup>(1,2)</sup>	CN24PUE <sup>(1)</sup>	CN23PUE	CN22PUE	CN21PUE	CN20PUE <sup>(1,2)</sup>	CN19PUE <sup>(1,2)</sup>	CN18PUE <sup>(1,2)</sup>	CN17PUE <sup>(1,2)</sup>	CN16PUE <sup>(1)</sup>	0000
CNPU3	0072	_	_	—	_	_	_	_	_		—	_	CN36PUE <sup>(1,2)</sup>	CN35PUE <sup>(1,2)</sup>	CN34PUE <sup>(1,2)</sup>	CN33PUE <sup>(1,2)</sup>	CN32PUE <sup>(1,2)</sup>	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: These bits are not implemented in 20-pin devices.

2: These bits are not implemented in 28-pin devices.

3: These bits are not implemented in FV devices.

## TABLE 4-8: OUTPUT COMPARE REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
OC1CON1	0190		_	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	ENFLT2	ENFLT1	ENFLT0	OCFLT2	OCFLT1	OCFLT0	TRIGMODE	OCM2	OCM1	OCM0	0000
OC1CON2	0192	FLTMD	FLTOUT	FLTTRIEN	OCINV		DCB1	DCB0	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC1RS	0194		OC1RS											0000				
OC1R	0196									OC1R								0000
OC1TMR	0198									OC1TMR								xxxx
OC2CON1	019A	_	_	OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	ENFLT2	ENFLT1	ENFLT0	OCFLT2	OCFLT1	OCFLT0	TRIGMODE	OCM2	OCM1	OCM0	0000
OC2CON2	019C	FLTMD	FLTOUT	FLTTRIEN	OCINV		DCB1	DCB0	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC2RS	019E									OC2RS								0000
OC2R	01A0									OC2R								0000
OC2TMR	01A2									OC2TMR								XXXX
OC3CON1	01A4			OCSIDL	OCTSEL2	OCTSEL1	OCTSEL0	ENFLT2	ENFLT1	ENFLT0	OCFLT2	OCFLT1	OCFLT0	TRIGMODE	OCM2	OCM1	OCM0	0000
OC3CON2	01A6	FLTMD	FLTOUT	FLTTRIEN	OCINV		DCB1	DCB0	OC32	OCTRIG	TRIGSTAT	OCTRIS	SYNCSEL4	SYNCSEL3	SYNCSEL2	SYNCSEL1	SYNCSEL0	000C
OC3RS	01A8									OC3RS								0000
OC3R	01AA		OC3R 00										0000					
OC3TMR	01AC									OC3TMR								XXXX

**Legend:** — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

NOTES:

### 10.2.4.2 Exiting Deep Sleep Mode

Deep Sleep mode exits on any one of the following events:

- A POR event on VDD supply. If there is no DSBOR circuit to re-arm the VDD supply POR circuit, the external VDD supply must be lowered to the natural arming voltage of the POR circuit.
- A DSWDT time-out. When the DSWDT timer times out, the device exits Deep Sleep.
- An RTCC alarm (if RTCEN = 1).
- An assertion ('0') of the MCLR pin.
- An assertion of the INT0 pin (if the interrupt was enabled before Deep Sleep mode was entered). The polarity configuration is used to determine the assertion level ('0' or '1') of the pin that will cause an exit from Deep Sleep mode. Exiting from Deep Sleep mode requires a change on the INT0 pin while in Deep Sleep mode.

Note: Any interrupt pending when entering Deep Sleep mode is cleared.

Exiting Deep Sleep mode generally does not retain the state of the device and is equivalent to a Power-on Reset (POR) of the device. Exceptions to this include the RTCC (if present), which remains operational through the wake-up, the DSGPRx registers and DSWDT.

Wake-up events that occur after Deep Sleep exits, but before the POR sequence completes, are ignored and are not be captured in the DSWAKE register.

The sequence for exiting Deep Sleep mode is:

- 1. After a wake-up event, the device exits Deep Sleep and performs a POR. The DSEN bit is cleared automatically. Code execution resumes at the Reset vector.
- To determine if the device exited Deep Sleep, read the Deep Sleep bit, DPSLP (RCON<10>). This bit will be set if there was an exit from Deep Sleep mode; if the bit is set, clear it.
- 3. Determine the wake-up source by reading the DSWAKE register.
- Determine if a DSBOR event occurred during Deep Sleep mode by reading the DSBOR bit (DSCON<1>).
- 5. If application context data has been saved, read it back from the DSGPR0 and DSGPR1 registers.
- 6. Clear the RELEASE bit (DSCON<0>).

# 10.2.4.3 Saving Context Data with the DSGPR0/DSGPR1 Registers

As exiting Deep Sleep mode causes a POR, most Special Function Registers reset to their default POR values. In addition, because VCORE power is not supplied in Deep Sleep mode, information in data RAM may be lost when exiting this mode. Applications which require critical data to be saved prior to Deep Sleep may use the Deep Sleep General Purpose registers, DSGPR0 and DSGPR1 or data EEPROM (if available). Unlike other SFRs, the contents of these registers are preserved while the device is in Deep Sleep mode. After exiting Deep Sleep, software can restore the data by reading the registers and clearing the RELEASE bit (DSCON<0>).

### 10.2.4.4 I/O Pins During Deep Sleep

During Deep Sleep, the general purpose I/O pins retain their previous states and the Secondary Oscillator (SOSC) will remain running, if enabled. Pins that are configured as inputs (TRISx bit is set), prior to entry into Deep Sleep, remain high-impedance during Deep Sleep. Pins that are configured as outputs (TRISx bit is clear), prior to entry into Deep Sleep, remain as output pins during Deep Sleep. While in this mode, they continue to drive the output level determined by their corresponding LATx bit at the time of entry into Deep Sleep.

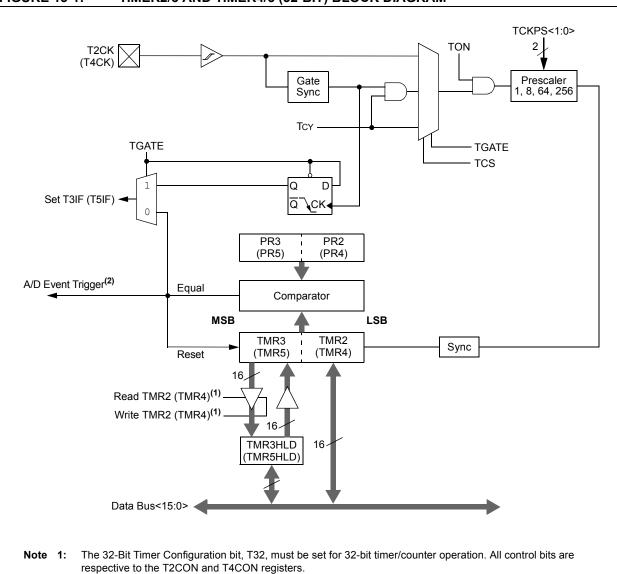
Once the device wakes back up, all I/O pins continue to maintain their previous states, even after the device has finished the POR sequence and is executing application code again. Pins configured as inputs during Deep Sleep remain high-impedance and pins configured as outputs continue to drive their previous value. After waking up, the TRIS and LAT registers, and the SOSCEN bit (OSCCON<1>) are reset. If firmware modifies any of these bits or registers, the I/O will not immediately go to the newly configured states. Once the firmware clears the RELEASE bit (DSCON<0>), the I/O pins are "released". This causes the I/O pins to take the states configured by their respective TRISx and LATx bit values.

This means that keeping the SOSC running after waking up requires the SOSCEN bit to be set before clearing RELEASE.

If the Deep Sleep BOR (DSBOR) is enabled, and a DSBOR or a true POR event occurs during Deep Sleep, the I/O pins will be immediately released, similar to clearing the RELEASE bit. All previous state information will be lost, including the general purpose DSGPR0 and DSGPR1 contents.

If a MCLR Reset event occurs during Deep Sleep, the DSGPRx, DSCON and DSWAKE registers will remain valid, and the RELEASE bit will remain set. The state of the SOSC will also be retained. The I/O pins, however, will be reset to their MCLR Reset state. Since RELEASE is still set, changes to the SOSCEN bit (OSCCON<1>) cannot take effect until the RELEASE bit is cleared.

In all other Deep Sleep wake-up cases, application firmware must clear the RELEASE bit in order to reconfigure the I/O pins.



### FIGURE 13-1: TIMER2/3 AND TIMER4/5 (32-BIT) BLOCK DIAGRAM

2: The A/D event trigger is available only on Timer2/3 and Timer4/5 in 32-bit mode, and Timer3 and Timer5 in 16-bit mode.

R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
TON	_	TSIDL				_	_
bit 15		1					bit
U-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0
	TGATE	TCKPS1	TCKPS0	T32 <sup>(1)</sup>	_	TCS	—
bit 7							bit
Legend:							
R = Readable	e bit	W = Writable	bit	U = Unimplen	nented bit, read	d as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is clea	ared	x = Bit is unkno	own
bit 15	TON: Timerx	On hit					
	When TxCON						
	1 = Starts 32	-bit Timerx/y					
	0 = Stops 32	-					
	When TxCON 1 = Starts 16						
	0 = Stops 16						
bit 14	Unimplemen	ted: Read as '	0'				
bit 13	TSIDL: Timer	x Stop in Idle N	/lode bit				
		ues module op s module opera		evice enters Id de	le mode		
bit 12-7	Unimplemen	ted: Read as '	0'				
bit 6	TGATE: Time	erx Gated Time	Accumulation	Enable bit			
	When TCS =						
	This bit is igno When TCS =						
		<u>o.</u> ne accumulatio	n is enabled				
	0 = Gated tin	ne accumulatio	n is disabled				
bit 5-4	TCKPS<1:0>	: Timerx Input	Clock Prescale	e Select bits			
	11 = 1:256						
	10 = 1:64 01 = 1:8						
	00 = 1:1						
bit 3		mer Mode Sele					
				er5 form a singl er5 act as two 1			
bit 2	Unimplemen	ted: Read as '	0'				
bit 1	TCS: Timerx	Clock Source S	Select bit				
		clock from pin clock (Fosc/2)	, TxCK (on the	rising edge)			
			0'				
bit 0	Unimplemen	ted: Read as '	0				

### REGISTER 17-3: I2CxMSK: I2Cx SLAVE MODE ADDRESS MASK REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—		—	—	—	AMSK9	AMSK8
bit 15							bit 8

| R/W-0 |
|-------|-------|-------|-------|-------|-------|-------|-------|
| AMSK7 | AMSK6 | AMSK5 | AMSK4 | AMSK3 | AMSK2 | AMSK1 | AMSK0 |
| bit 7 |       |       |       |       |       |       | bit 0 |

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-10 Unimplemented: Read as '0'

bit 9-0 AMSK<9:0>: Mask for Address Bit x Select bits

1 = Enables masking for bit x of an incoming message address; bit match is not required in this position
 0 = Disables masking for bit x; bit match is required in this position

### REGISTER 17-4: PADCFG1: PAD CONFIGURATION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0
_	—	SMBUSDEL2	SMBUSDEL1		—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read a	as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-6 Unimplemented: Read as '0'

bit 5	SMBUSDEL2: SMBus SDA2 Input Delay Select bit
	<ul> <li>1 = The I2C2 module is configured for a longer SMBus input delay (nominal 300 ns delay)</li> <li>0 = The I2C2 module is configured for a legacy input delay (nominal 150 ns delay)</li> </ul>
bit 4	SMBUSDEL1: SMBus SDA1 Input Delay Select bit
	<ul> <li>1 = The I2C1 module is configured for a longer SMBus input delay (nominal 300 ns delay)</li> <li>0 = The I2C1 module is configured for a legacy input delay (nominal 150 ns delay)</li> </ul>
bit 3-0	Unimplemented: Read as '0'

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—		—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8
U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit (

### REGISTER 19-6: WKDYHR: WEEKDAY AND HOURS VALUE REGISTER<sup>(1)</sup>

Legend:					
R = Readable bit	Readable bit W = Writable bit U = Unimplemented bit, read as '0'				
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown		

bit 15-11	Unimplemented: Read as '0'
bit 10-8	WDAY<2:0>: Binary Coded Decimal Value of Weekday Digit bits
	Contains a value from 0 to 6.
bit 7-6	Unimplemented: Read as '0'
bit 5-4	HRTEN<1:0>: Binary Coded Decimal Value of Hour's Tens Digit bits
	Contains a value from 0 to 2.
bit 3-0	HRONE<3:0>: Binary Coded Decimal Value of Hour's Ones Digit bits
	Contains a value from 0 to 9.

**Note 1:** A write to this register is only allowed when RTCWREN = 1.

### REGISTER 19-7: MINSEC: MINUTES AND SECONDS VALUE REGISTER

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	
—	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0	
bit 15							bit 8	
U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	
_	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0	
bit 7							bit 0	
Legend:								
R = Readable	bit	W = Writable	oit	U = Unimplemented bit, read as '0'				
-n = Value at POR '1' = Bit is set				'0' = Bit is cleared x = Bit is unknown				
bit 15	Unimplemen	ted: Read as 'd	)'					

bit 14-12 MINTEN<2:0>: Binary Coded Decimal Value of Minute's Tens Digit bits Contains a value from 0 to 5. bit 11-8 MINONE<3:0>: Binary Coded Decimal Value of Minute's Ones Digit bits Contains a value from 0 to 9. bit 7 Unimplemented: Read as '0' bit 6-4 SECTEN<2:0>: Binary Coded Decimal Value of Second's Tens Digit bits Contains a value from 0 to 5. bit 3-0 SECONE<3:0>: Binary Coded Decimal Value of Second's Ones Digit bits Contains a value from 0 to 9.

bit 8

bit 0

U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	
	MINTEN2	MINTEN1	MINTEN0	MINONE3	MINONE2	MINONE1	MINONE0	
bit 15							bit 8	
U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	
—	SECTEN2	SECTEN1	SECTEN0	SECONE3	SECONE2	SECONE1	SECONE0	
bit 7							bit 0	
Legend:								
R = Readab	le bit	W = Writable	U = Unimplemented bit, read as '0'					
-n = Value a	t POR	'1' = Bit is set		'0' = Bit is cleared x = Bit is unknown				
bit 15	Unimplement	ted: Read as '0	,					
bit 14-12	MINTEN<2:0	>: Binary Code	d Decimal Valu	ue of Minute's T	ens Digit bits			
	Contains a va	lue from 0 to 5						
bit 11-8	MINONE<3:0	>: Binary Code	d Decimal Val	ue of Minute's 0	Ones Digit bits			
	Contains a va	lue from 0 to 9						
bit 7	Unimplemen	ted: Read as '	o'					
bit 6-4	SECTEN<2:0	>: Binary Code	ed Decimal Val	ue of Second's	Tens Digit bits			
	Contains a va	lue from 0 to 5						
bit 3-0	SECONE<3:0	>: Binary Code	ed Decimal Va	lue of Second's	Ones Digit bits	6		
	Contains a va	lue from 0 to 9						

### REGISTER 19-10: ALMINSEC: ALARM MINUTES AND SECONDS VALUE REGISTER

Alarm Mask Setting (AMASK<3:0>)	Day of the Week	Month	Day	Hours	Minutes	Seconds
0000 - Every half second 0001 - Every second						•
0010 - Every 10 seconds					•	s
0011 - Every minute					:	s s
0100 - Every 10 minutes					<b>m</b>	ss
0101 - Every hour					mm	ss
0110 - Every day				hh	mm	ss
0111 - Every week	d			hh	mm	ss
1000 - Every month			d d	hh	mm	ss
1001 - Every year <sup>(1)</sup>		<b>m m</b> /	d d	hh	mm	ss
Note 1: Annually, except whe	n configured fo	r February 29				

### 19.5 POWER CONTROL

The RTCC includes a power control feature that allows the device to periodically wake-up an external device, wait for the device to be stable before sampling wake-up events from that device and then shut down the external device. This can be done completely autonomously by the RTCC, without the need to wake from the current low-power mode (Sleep, Deep Sleep, etc.).

To enable this feature, the RTCC must be enabled (RTCEN = 1), the PWCEN register bit must be set and the RTCC pin must be driving the PWC control signal (RTCOE = 1 and RTCOUT<1:0> = 11).

The polarity of the PWC control signal may be chosen using the PWCPOL register bit. Active-low or active-high may be used with the appropriate external switch to turn on or off the power to one or more external devices. The active-low setting may also be used in conjunction with an open-drain setting on the RTCC pin. This setting is able to drive the GND pin(s) of the external device directly (with the appropriate external VDD pull-up device), without the need for external switches. Finally, the CHIME bit should be set to enable the PWC periodicity.

### 27.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

### 27.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

### 27.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel<sup>®</sup> standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- · Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

### 27.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

### 27.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- · Support for the entire device instruction set
- · Support for fixed-point and floating-point data
- Command line interface
- · Rich directive set
- · Flexible macro language
- · MPLAB IDE compatibility

DC CHARAC	CTERISTICS	$ \begin{array}{llllllllllllllllllllllllllllllllllll$								
Parameter No.	Device	Typical <sup>(1)</sup>	Max	Units		Conditions				
Module Diffe	erential Current (∆IPD	) <sup>(3)</sup>								
DC78	PIC24FV32KA3XX	0.03	_	μA	-40°C	2.0V				
		0.05	0.20	μA	+85°C	5.0V				
			0.30	μA	+125°C	5.0V	Deep Sleep BOR:			
	PIC24F32KA3XX	0.03	_	μA	-40°C	1.8V	$\Delta$ ILPBOR <sup>(5)</sup>			
		0.05	0.20	μA	+85°C	3.3V				
		_	0.30	μA	+125°C	3.3V				
DC80	PIC24FV32KA3XX	0.20	_	μA	-40°C	2.0V				
		0.70	1.5	μA	+85°C	5.0V				
			1.5	μA	+125°C	5.0V	Deep Sleep WDT:			
	PIC24F32KA3XX	0.20		μA	-40°C	1.8V	∆ldswdt (LPRC) <sup>(6)</sup>			
		0.35	0.8	μA	+85°C	3.3V				
		_	1.5	μA	+125°C	3.3V				

### TABLE 29-8: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD) (CONTINUED)

Legend: Unshaded rows represent PIC24F32KA3XX devices and shaded rows represent PIC24FV32KA3XX devices. Note 1: Data in the Typical column is at 3.3V, +25°C (PIC24F32KA3XX) or 5.0V, +25°C (PIC24FV32KA3XX) unless

otherwise stated. Parameters are for design guidance only and are not tested.

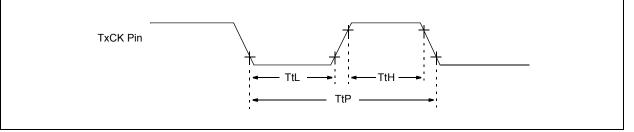
Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as outputs and set low, 2: PMSLP is set to '0' and WDT, etc., are all switched off.

3: The  $\Delta$  current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

4: This current applies to Sleep only.

5: This current applies to Sleep and Deep Sleep.6: This current applies to Deep Sleep only.

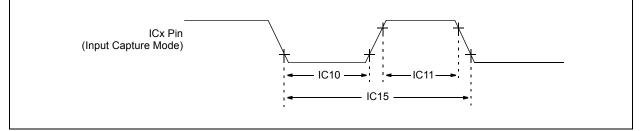
### FIGURE 29-8: TIMER1/2/3/4/5 EXTERNAL CLOCK INPUT TIMING



### TABLE 29-27: TIMER1/2/3/4/5 EXTERNAL CLOCK INPUT REQUIREMENTS

Param. No.	Symbol	Chara	Min	Max	Units	Conditions	
	TtH	TxCK High Pulse	Sync w/Prescaler	Tcy + 20	_	ns	Must also meet
		Time	Async w/Prescaler	10	_	ns	Parameter Ttp
			Async Counter	20	_	ns	
	TtL TxCK Low Pulse		Sync w/Prescaler	Tcy + 20	_	ns	Must also meet
		Time	Async w/Prescaler	10	_	ns	Parameter Ttp
			Async Counter	20	_	ns	
	TtP	TxCK External Input	Sync w/Prescaler	2 * Tcy + 40	_	ns	N = Prescale Value
		Period	Async w/Prescaler	Greater of: 20 or <u>2 * Tcy + 40</u> N	—	ns	(1, 4, 8, 16)
			Async Counter	40		ns	
		Delay for Input Edge	Synchronous	1	2	TCY	
		to Timer Increment	Asynchronous	—	20	ns	

### FIGURE 29-9: INPUT CAPTURE x TIMINGS



### TABLE 29-28: INPUT CAPTURE x REQUIREMENTS

Param. No.	Symbol	Characteristic		Min	Мах	Units	Conditions
IC10	TccL	ICx Input Low Time –	No Prescaler	Tcy + 20	—	ns	Must also meet
		Synchronous Timer	With Prescaler	20	_	ns	Parameter IC15
IC11	ТссН	ICx Input Low Time –	No Prescaler	Tcy + 20	—	ns	Must also meet
		Synchronous Timer	With Prescaler	20	—	ns	Parameter IC15
IC15	TccP	ICx Input Period – Syncl	nronous Timer	<u>2 * Tcy + 40</u> N	—	ns	N = prescale value (1, 4, 16)

# FIGURE 29-12: I<sup>2</sup>C<sup>TM</sup> BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

### TABLE 29-31: I<sup>2</sup>C<sup>™</sup> BUS START/STOP BIT TIMING REQUIREMENTS (MASTER MODE)

				$\begin{array}{l} \mbox{Standard Operating Conditions: 2.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial)} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$					
Param No.	<sup>1</sup> Symbol Characteristic			Min <sup>(1)</sup>	Max	Units	Conditions		
IM30	TSU:STA	Start Condition	100 kHz mode	Tcy/2 (BRG + 1)		μS	Only relevant for		
		Setup Time	400 kHz mode	Tcy/2 (BRG + 1)	_	μS	Repeated Start		
			1 MHz mode <sup>(2)</sup>	Tcy/2 (BRG + 1)	_	μS	condition		
IM31	THD:STA	Start Condition	100 kHz mode	Tcy/2 (BRG + 1)	—	μS	After this period, the		
		Hold Time	400 kHz mode	Tcy/2 (BRG + 1)	—	μS	first clock pulse is		
			1 MHz mode <sup>(2)</sup>	Tcy/2 (BRG + 1)	—	μS	generated		
IM33	Tsu:sto	Stop Condition	100 kHz mode	TCY/2 (BRG + 1)	—	μS			
		Setup Time	400 kHz mode	Tcy/2 (BRG + 1)	—	μS			
			1 MHz mode <sup>(2)</sup>	Tcy/2 (BRG + 1)	—	μS			
IM34	THD:STO	Stop Condition	100 kHz mode	Tcy/2 (BRG + 1)	—	ns			
		Hold Time	400 kHz mode	Tcy/2 (BRG + 1)	_	ns			
			1 MHz mode <sup>(2)</sup>	Tcy/2 (BRG + 1)	—	ns			

Note 1: BRG is the value of the l<sup>2</sup>C<sup>™</sup> Baud Rate Generator. Refer to Section 17.3 "Setting Baud Rate When Operating as a Bus Master" for details.

2: Maximum pin capacitance = 10 pF for all I<sup>2</sup>C pins (for 1 MHz mode only).

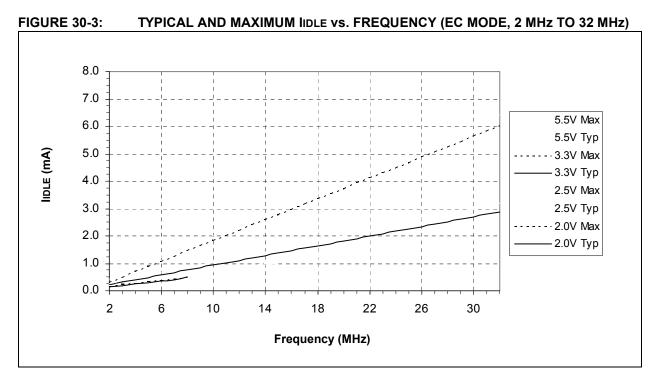
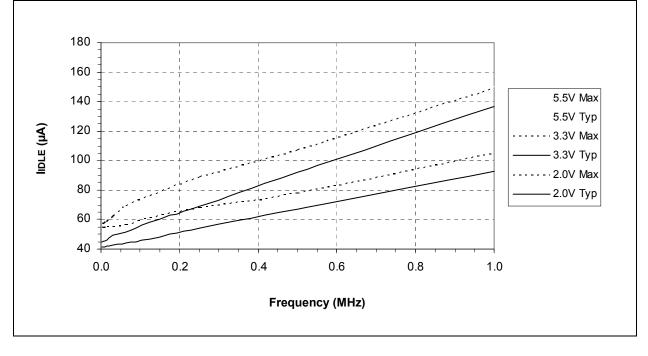
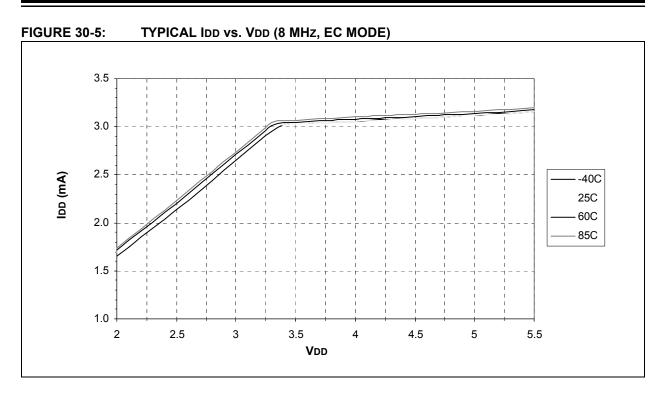


FIGURE 30-4: TYPICAL AND MAXIMUM lidle vs. FREQUENCY (EC MODE, 1.95 kHz TO 1 MHz)







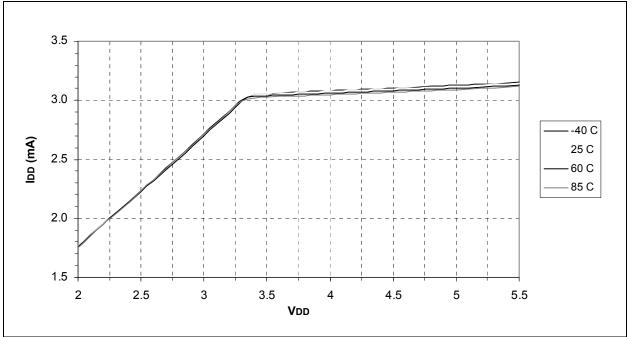
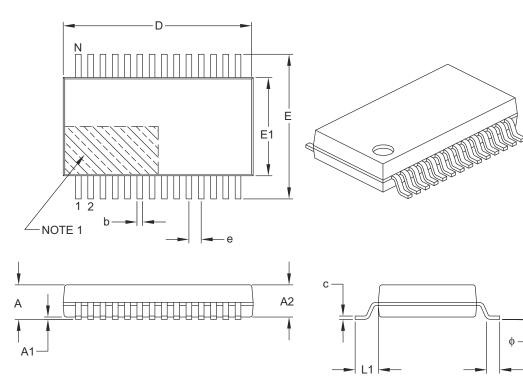


FIGURE 30-48: TYPICAL AIHLVD VS. VDD

### 28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units				
Dimensio	on Limits	MIN	NOM	MAX	
Number of Pins	Ν		28		
Pitch	е		0.65 BSC		
Overall Height	А	-	-	2.00	
Molded Package Thickness	A2	1.65	1.75	1.85	
Standoff	A1	0.05	-	_	
Overall Width	Е	7.40	7.80	8.20	
Molded Package Width	E1	5.00	5.30	5.60	
Overall Length	D	9.90	10.20	10.50	
Foot Length	L	0.55	0.75	0.95	
Footprint	L1		1.25 REF		
Lead Thickness	С	0.09	-	0.25	
Foot Angle	ф	0°	4°	8°	
Lead Width	b	0.22	-	0.38	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
 Dimensioning and tolerancing per ASME Y14.5M.

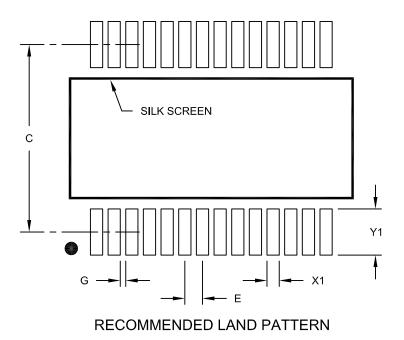
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units				
Dimension	MIN	NOM	MAX		
Contact Pitch	E	0.65 BSC			
Contact Pad Spacing	С		7.20		
Contact Pad Width (X28)	X1			0.45	
Contact Pad Length (X28)	Y1			1.75	
Distance Between Pads	G	0.20			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

NOTES: